

IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A substrate holder, comprising:  
a plate member having a first nominal size receivable by a lithographic apparatus, said plate member having a receiving surface on which a substrate of a second nominal size is disposed, and said plate member being configured to substantially entirely support a lower surface of said substrate; and  
a clamp constructed and arranged to hold a said substrate of a second nominal size on the plate member, the second nominal size being smaller than the first nominal size, wherein said lithographic apparatus is originally configured to expose substrates having substantially said first nominal size, and  
wherein the clamp comprises a ring of magnetic material having an inner contour similar to but smaller than the outer contour of the substrate of a second nominal size and a plurality of magnets are fixed to the plate member.
2. (Currently Amended) A substrate holder according to claim 1, wherein the clamp is adapted to hold the substrate of a second nominal size around substantially an entire periphery of the substrate.
3. (Currently Amended) A substrate holder according to claim 1, wherein ~~an unimageable~~ a portion of the substrate of a second nominal size that is not imaged during exposure with said lithographic apparatus is a peripheral portion of about 3mm wide.
4. (Original) A substrate holder according to claim 1, wherein the plate member comprises a silicon wafer to which the clamp is attached.
5. (Original) A substrate holder according to claim 1, wherein the plate member is substantially circular and ~~optionally has~~ includes one or more flats or notches.
6. (Original) A substrate holder according to claim 1, wherein the first nominal size is 150 mm or larger and the second nominal size is 100 mm or smaller.

7. (Original) A substrate holder according to claim 1, wherein the plate member has one or more positioning pins located such that when the substrate is abutted against the one or more positioning pins the substrate is located at a predetermined position and orientation on the plate member.

8. (Original) A substrate holder according to claim 7, for use with a substrate having one or more flats or notches, wherein the plate member is provided with one or more flats or notches and the one or more positioning pins are located such that the one or more flats or notches of the substrate are in a predetermined, corresponding orientation to the one or more flats or notches of the plate member.

9. (Cancelled).

10. (Original) A substrate holder according to claim 1, wherein the plate member includes a burl pattern in a region on which the substrate is to be held.

11. (Currently Amended) A method of operating a substrate holder according to claim 1, the method comprising:  
locating the plate member on a platform;  
placing the substrate on the plate member in a correct orientation;  
locating the clamp on a chuck; and  
lowering the chuck onto the platform to locate the clamp over the substrate to thereby clamp the substrate to the plate member.

12. (Original) A method according to claim 11, wherein the lowering comprises:  
locating holes in the chuck with pins on the platform to align the clamp, the substrate and the plate member.

13. (Original) A method according to claim 11, wherein locating the clamp on a chuck includes applying a vacuum to the chuck.

14. (Currently Amended) A device manufacturing method, comprising:  
~~providing a substrate that is at least partially covered by a layer of radiation-sensitive material, wherein providing the substrate comprises~~  
disposing a substrate on a receiving surface of a plate member, said plate member being configured to substantially entirely support a lower surface of said substrate;  
clamping the substrate to a the plate member, said plate member having a first nominal size larger than a second nominal size of the substrate;  
loading the plate member having the substrate clamped thereto in a lithographic apparatus; and  
projecting a patterned beam of radiation onto a target ~~portion~~ portion of the ~~a~~ layer of radiation-sensitive material disposed on an upper surface of said substrate  
wherein said lithographic apparatus is originally configured to expose substrates having substantially said first nominal size, and  
wherein the substrate is clamped to the plate member magnetically.

15. (Original) A device manufacturing method according to claim 14, wherein clamping the substrate comprises clamping the substrate around substantially an entire periphery of the substrate.

16. (Original) A device manufacturing method according to claim 14, wherein providing the substrate further comprises:

abutting the substrate against one or more positioning pins on the plate member such that when the substrate is abutted against the one or more positioning pins the substrate is located at a predetermined position and orientation on the plate member.

17. (Original) A device manufacturing method according to claim 16, wherein the plate member is provided with one or more flats or notches and the one or more positioning pins are located such that the one or more flats or notches of the substrate are in a predetermined, corresponding orientation to the one or more flats or notches of the plate member.

18. (Original) A device manufacturing method according to claim 14, wherein providing the substrate further comprises locating the substrate on a burl pattern on the plate member.

19. (Cancelled).

20. (Currently Amended) A device manufacturing method according to claim 14, wherein loading the plate member having the substrate clamped thereto in a lithographic apparatus comprises:

locating the plate member on a platform;

placing the substrate on the plate member in a correct orientation;

locating the clamp on a chuck; and

lowering the chuck onto the platform to locate the clamp over the substrate to thereby clamp the substrate to the plate member.